

# **Final Product Change Notification**

Issue Date: 06-May-2020 Effective Date: 04-Aug-2020 Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP. For detailed information we invite you to <u>view this</u> notification online

### This notice is NXP Company Proprietary.

# 202004018F01



#### **Management Summary**

Second sourcing waferfab production for TEA19162T/2, TEA19162T/3 and TEA19162HT/2 in ICN8. Change Category

	r 1	[] Due duret Merilia a	[] ] ]	[] Decim
[] Water Fab Process		[] Product Marking	[] lest	[] Design
	Assembly		Location	
	Process			
[] Wafer Fab Materials	[]	[] Mechanical	[]Test	[] Errata
	Assembly	Specification	Process	
	Materials			
[X] Wafer Fab Location	[]	[]	[] Test	[] Electrical
	Assembly	Packing/Shipping/Labeling	g Equipment	spec./Test
	Location			coverage
[] Firmware	[] Other			-
Change in Order to				
Guarantee the Supply to				
Customers in the Current				
Time Second Source				
Watertab ICN8 for				
TEA19162*				

### **Description of Change**

Change in order to guarantee the supply to customers in the current time, internal second source waferfab for TEA19162T/2, TEA19162T/3 and TEA19162HT/2 in ICN8 next to Vanguard (VIS). **Reason for Change** To guarantee the supply to customers a second source (ICN-8) will be released for TEA19162T/2, TEA19162T/3 and TEA19162HT/2. **Identification of Affected Products** Top side marking Top side marking for the first and second line will remain the same for all 3 types: 1: TEA19162T/2, TEA19162T/3: EA19162 1: TEA19162HT/2: A19162H 2: DBID & ASID Top side marking will change for all 3 types on the third line from: rXDyww2 (VIS) to 3: TEA19162T/2 to TXDyww2 (ICN8) 3: TEA19162HT/2 to TXDyww3 (ICN8) 3: TEA19162HT/2 to TXDyww2 (ICN8)

Product Availability			
Sample Information			
Samples are available upon request			
Production			
Planned first shipment 03-Aug-2020			
Anticipated Impact on Form, Fit, Function, Reliability or Quality			
No impact on form, fit, function, reliability or quality.			
Data Sheet Revision			
No impact to existing datasheet			
Disposition of Old Products			
Existing inventory will be shipped until depleted			
Additional information			
Affected products and sales history information: see attached file			
Self qualification: view online			
Additional documents: view online			
Timing and Logistics			
In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 05-Jun-2020.			
n.a.			
Remarks			
n.a.			
Contact and Support			

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality</u> <u>Support Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:NameJoost Haaren, vanPositionBL Smart Power Quality Engineere-mail addressjoost.van.haaren@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your

## organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	<u>Support</u>
NXP   Privacy Policy   Terms of Use		
NVD Comission durations		

NXP Semiconductors High Tech Campus, 5656 AG Eindhoven, The Netherlands © 2006-2010 NXP Semiconductors. All rights reserved.